

8327GL3



Non-Silicone Liquid Thermal Gel

8327GL3 is a 1-part, silicone-free, ultra soft gel offering high thermal conductivity and flame retardancy. This form-in-place, non-curable gel is easy to dispense and conforms to the component/heatsink interface, ensuring all air is displaced and eliminating hotspots. Since the gel does not cure, circuits can be powered up immediately following application, offering exceptional convenience.

It is most often used as a gap filler on heatsinks to CPUs, LEDs, and other electronic components. Its high thermal conductivity makes it ideal for energy-intensive devices like telecommunications equipment, PCs for gamers and electric vehicle battery packs.



Features & Benefits

- High thermal conductivity
- Flame retardant—meets UL94 V-0
- 1-part, non-curable, dispensable gel
- Silicone-free, will not contaminate surfaces
- Low modulus, ideal for aggressive thermal cycling conditions

Properties

Color	White	—
Density	2.5 g/mL	Hydrostatic Weighing
Service Temperature Range	-40–120 °C	—
Intermittent Temperature	150 °C	—
Resistivity	10 ¹³ Ω·cm	ASTM D257
Dissipation Factor @ 1 kHz	0.005	—
Breakdown Voltage @ 1 mm	14 000 V	—
Thermal Conductivity @ 25 °C	3.5 W/(m·K)	ASTM E1461
Flow Rate @ 90 psi, 0.1" orifice	5–7 g/min	—
Viscosity @ 25 °C	7 000 Pa·s	Brookfield Engineering labs Inc. IPCTM-65- Method 2.4.24.4
Shelf Life	2 y	—

Available Packaging

Part #	Packaging	Net Wt.
8327GL3-25ML	Jar	67 g
8327GL3-30ML	Cartridge	66 g
8327GL3-180ML	Cartridge	294

Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight (see SDS). To maximize shelf life, recap product firmly when not in use.